

RF Power Field Effect Transistors

N-Channel Enhancement-Mode Lateral MOSFETs

Designed primarily for CW large-signal output and driver applications at 2450 MHz. Devices are suitable for use in industrial, medical and scientific applications.

- Typical CW Performance: $V_{DD} = 28$ Volts, $I_{DQ1} = 55$ mA, $I_{DQ2} = 195$ mA, $P_{out} = 25$ Watts CW, $f = 2450$ MHz
 Power Gain — 27.7 dB
 Power Added Efficiency — 43.8%
- Capable of Handling 10:1 VSWR, @ 28 Vdc, 2450 MHz, 25 Watts CW Output Power

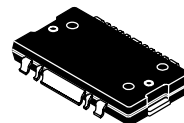
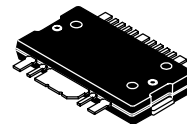
Features

- Qualified Up to a Maximum of 28 V_{DD} Operation
- Integrated Quiescent Current Temperature Compensation with Enable/Disable Function (1)
- Integrated ESD Protection
- Excellent Thermal Stability
- 225°C Capable Plastic Package
- RoHS Compliant
- In Tape and Reel. R1 Suffix = 500 Units per 44 mm, 13 inch Reel.

MW7IC2425NR1
MW7IC2425GNR1
MW7IC2425NBR1

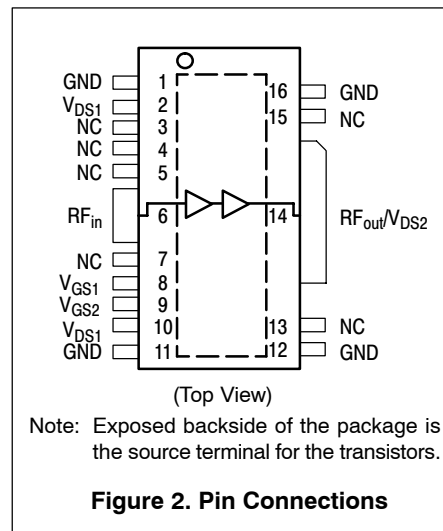
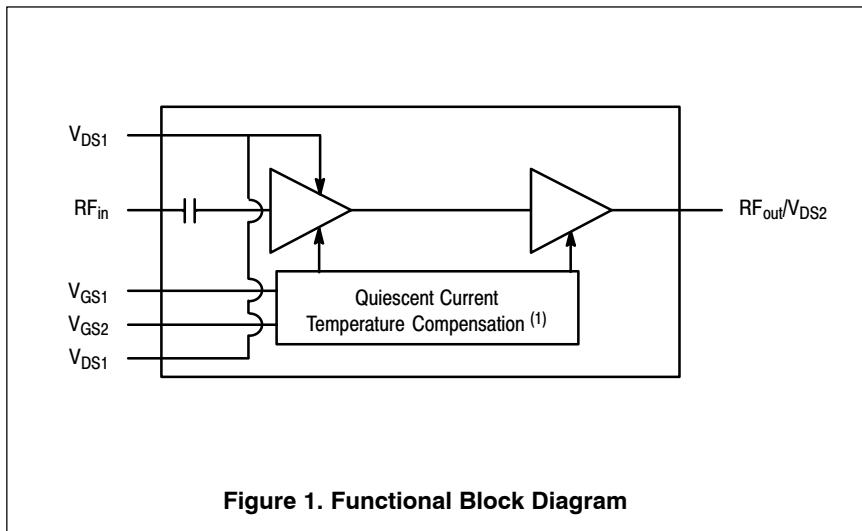
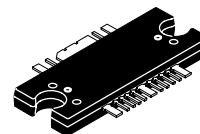
2450 MHz, 25 W CW, 28 V
LATERAL N-CHANNEL
RF POWER MOSFETs

CASE 1886-01
TO-270 WB-16
PLASTIC
MW7IC2425NR1



CASE 1887-01
TO-270 WB-16 GULL
PLASTIC
MW7IC2425GNR1

CASE 1329-09
TO-272 WB-16
PLASTIC
MW7IC2425NBR1



1. Refer to AN1977, *Quiescent Current Thermal Tracking Circuit in the RF Integrated Circuit Family* and to AN1987, *Quiescent Current Control for the RF Integrated Circuit Device Family*. Go to <http://www.freescale.com/rf>. Select Documentation/Application Notes - AN1977 or AN1987.

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-0.5, +65	Vdc
Gate-Source Voltage	V_{GS}	-0.5, +10	Vdc
Operating Voltage	V_{DD}	32, +0	Vdc
Storage Temperature Range	T_{stg}	- 65 to +150	°C
Case Operating Temperature	T_C	150	°C
Operating Junction Temperature (1,2)	T_J	225	°C
Input Power	P_{in}	20	dBm

Table 2. Thermal Characteristics (In Freescale Narrowband Test Fixture)

Characteristic	Symbol	Value (2,3)	Unit
Thermal Resistance, Junction to Case (Case Temperature 80°C, $P_{out} = 25$ W CW)	$R_{\theta JC}$	6.1 1.2	°C/W
		Stage 1, 28 Vdc, $I_{DQ1} = 55$ mA	
		Stage 2, 28 Vdc, $I_{DQ2} = 195$ mA	

Table 3. ESD Protection Characteristics

Test Methodology	Class
Human Body Model (per JESD22-A114)	1B (Minimum)
Machine Model (per EIA/JESD22-A115)	A (Minimum)
Charge Device Model (per JESD22-C101)	II (Minimum)

Table 4. Moisture Sensitivity Level

Test Methodology	Rating	Package Peak Temperature	Unit
Per JESD22-A113, IPC/JEDEC J-STD-020	3	260	°C

Table 5. Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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Stage 1 - Off Characteristics

Zero Gate Voltage Drain Leakage Current ($V_{DS} = 65$ Vdc, $V_{GS} = 0$ Vdc)	I_{DSS}	—	—	10	μAdc
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 28$ Vdc, $V_{GS} = 0$ Vdc)	I_{DSS}	—	—	1	μAdc
Gate-Source Leakage Current ($V_{GS} = 1.5$ Vdc, $V_{DS} = 0$ Vdc)	I_{GSS}	—	—	1	μAdc

Stage 1 - On Characteristics

Gate Threshold Voltage ($V_{DS} = 10$ Vdc, $I_D = 20$ μAdc)	$V_{GS(th)}$	1.2	1.9	2.7	Vdc
Gate Quiescent Voltage ($V_{DS} = 28$ Vdc, $I_{DQ1} = 55$ mA) (4)	$V_{GS(Q)}$	—	2.7	—	Vdc
Fixture Gate Quiescent Voltage ($V_{DD} = 28$ Vdc, $I_{DQ1} = 55$ mA) (4,5)	$V_{GG(Q)}$	10.3	11.2	12.6	Vdc

1. Continuous use at maximum temperature will affect MTTF.
2. MTTF calculator available at <http://www.freescale.com/rf>. Select Software & Tools/Development Tools/Calculators to access MTTF calculators by product.
3. Refer to AN1955, *Thermal Measurement Methodology of RF Power Amplifiers*. Go to <http://www.freescale.com/rf>. Select Documentation/Application Notes - AN1955.
4. Measured in Freescale Narrowband Test Fixture.
5. See Appendix A for functional test measurements and test fixture.

(continued)

Table 5. Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted) (continued)

Characteristic	Symbol	Min	Typ	Max	Unit
Stage 2 - Off Characteristics					
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 65\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	10	μAdc
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 28\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	1	μAdc
Gate-Source Leakage Current ($V_{GS} = 1.5\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$)	I_{GSS}	—	—	1	μAdc

Stage 2 - On Characteristics

Gate Threshold Voltage ($V_{DS} = 10\text{ Vdc}$, $I_D = 80\ \mu\text{Adc}$)	$V_{GS(th)}$	1.2	1.9	2.7	Vdc
Gate Quiescent Voltage ($V_{DS} = 28\text{ Vdc}$, $I_{DQ2} = 195\text{ mAdc}$) (1)	$V_{GS(Q)}$	—	2.7	—	Vdc
Fixture Gate Quiescent Voltage ($V_{DD} = 28\text{ Vdc}$, $I_{DQ2} = 195\text{ mAdc}$) (1,2)	$V_{GG(Q)}$	9.5	10.5	11.5	Vdc
Drain-Source On-Voltage ($V_{GS} = 10\text{ Vdc}$, $I_D = 800\text{ mAdc}$)	$V_{DS(on)}$	0.15	0.47	0.8	Vdc

Stage 2 - Dynamic Characteristics (3)

Output Capacitance ($V_{DS} = 28\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{oss}	—	111	—	pF
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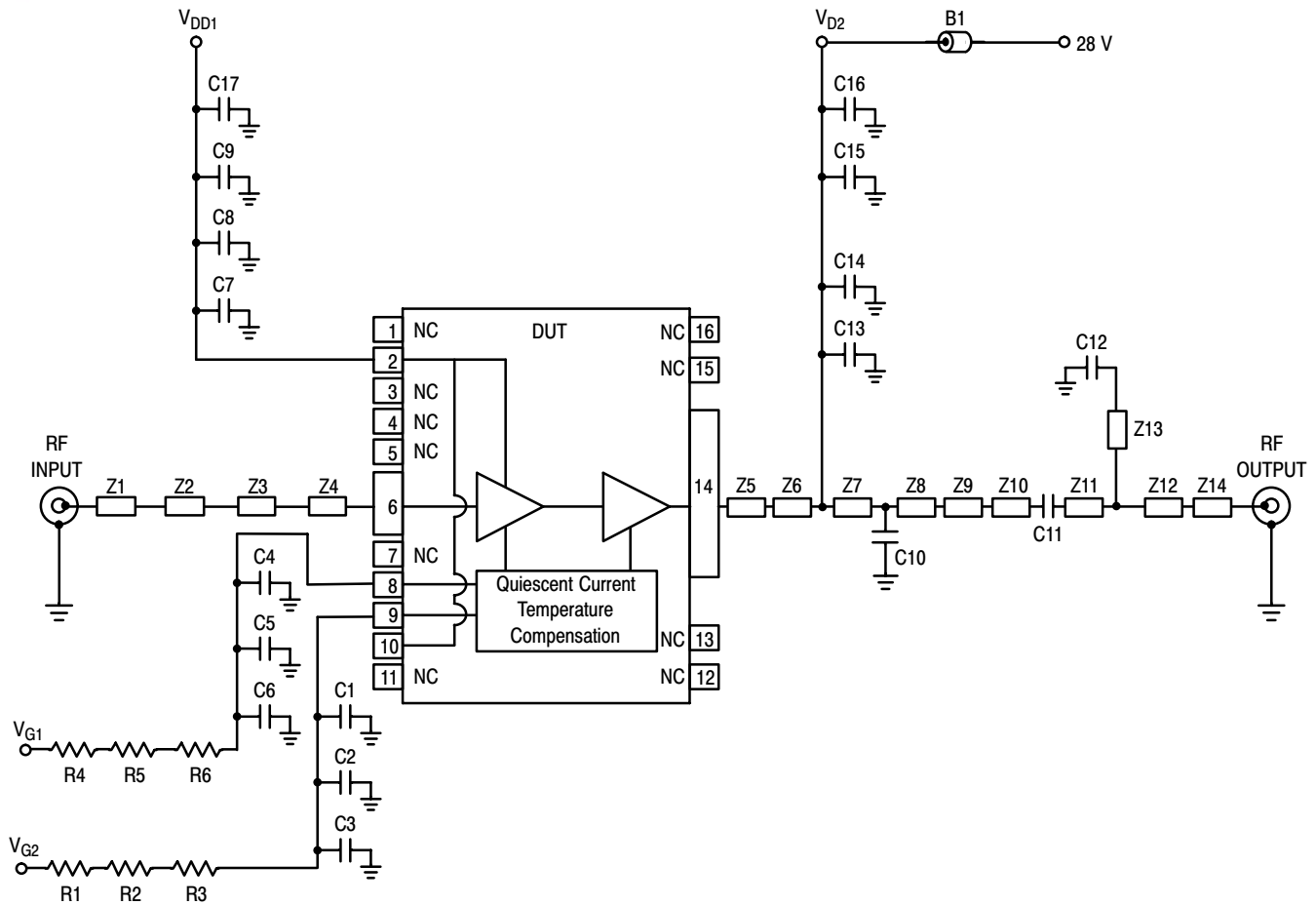
Narrowband Performance Specifications (4) (In Freescale Narrowband Test Fixture, (2) 50 ohm system) $V_{DD} = 28\text{ Vdc}$, $I_{DQ1} = 55\text{ mA}$, $I_{DQ2} = 195\text{ mA}$, $P_{out} = 25\text{ W CW}$, $f = 2450\text{ MHz}$

Power Gain	G_{ps}	25.5	27.7	30.5	dB
Power Added Efficiency	PAE	41.5	43.8	—	%
Input Return Loss	IRL	—	-18	-10	dB

Functional Tests (2) (In Freescale Test Fixture, 50 ohm system) $V_{DD} = 28\text{ Vdc}$, $I_{DQ1} = 77\text{ mA}$, $I_{DQ2} = 275\text{ mA}$, $P_{out} = 4\text{ W Avg.}$, $f = 2700\text{ MHz}$, WiMAX, OFDM 802.16d, 64 QAM $3/4$, 4 Bursts, 10 MHz Channel Bandwidth, Input Signal PAR = 9.5 dB @ 0.01% Probability on CCDF. ACPR measured in 1 MHz Channel Bandwidth @ $\pm 8.5\text{ MHz}$ Offset.

Power Gain	G_{ps}	25.5	28.5	30.5	dB
Power Added Efficiency	PAE	15	17	—	%
Output Peak-to-Average Ratio @ 0.01% Probability on CCDF	PAR	—	9	—	dB
Adjacent Channel Power Ratio	ACPR	—	-50	-46	dBc
Input Return Loss	IRL	—	-15	-10	dB

1. Measured in Freescale Narrowband Test Fixture.
2. See Appendix A for functional test fixture documentation.
3. Part internally matched both on input and output.
4. Measurement made with device in straight lead configuration before any lead forming operation is applied.



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|----|--------------------------------|------|--|
| Z1 | 0.500" x 0.027" Microstrip | Z9 | 0.040" x 0.061" Microstrip |
| Z2 | 0.075" x 0.127" Microstrip | Z10 | 0.020" x 0.050" Microstrip |
| Z3 | 1.640" x 0.027" Microstrip | Z11 | 0.050" x 0.050" Microstrip |
| Z4 | 0.100" x 0.042" Microstrip | Z12 | 0.050" x 0.027" Microstrip |
| Z5 | 0.151" x 0.268" Microstrip | Z13* | 0.338" x 0.020" Microstrip |
| Z6 | 0.025" x 0.268" x 0.056" Taper | Z14 | 1.551" x 0.027" Microstrip |
| Z7 | 0.100" x 0.056" Microstrip | PCB | Rogers R04350B, 0.0133", $\epsilon_r = 3.48$ |
| Z8 | 0.306" x 0.056" Microstrip | | |
- * Line length includes microstrip bends

Figure 3. MW7IC2425NR1 (GNR1)(NBR1) Narrowband Test Circuit Schematic

Table 6. MW7IC2425NR1 (GNR1)(NBR1) Narrowband Test Circuit Component Designations and Values

Part	Description	Part Number	Manufacturer
B1	47 Ω , 100 MHz Short Ferrite Bead	2743019447	Fair-Rite
C1, C4, C7, C12, C15	6.8 pF Chip Capacitors	ATC600S6R8CT250XT	ATC
C2, C5, C8, C13	10 nF Chip Capacitors	C0603C103J5RAC	Kemet
C3, C6, C9, C14	1 μ F, 50 V Chip Capacitors	GRM32RR71H105KA01B	Murata
C10	2.4 pF Chip Capacitor	ATC600S2R4BT250XT	ATC
C11	3.3 pF Chip Capacitor	ATC600S3R3BT250XT	ATC
C16, C17	10 μ F, 50 V Chip Capacitors	GRM55DR61H106KA88B	Murata
R1, R4	12 K Ω , 1/4 W Chip Resistors	CRCW12061202FKEA	Vishay
R2, R3, R5, R6	1 K Ω , 1/4 W Chip Resistors	CRCW12061001FKEA	Vishay

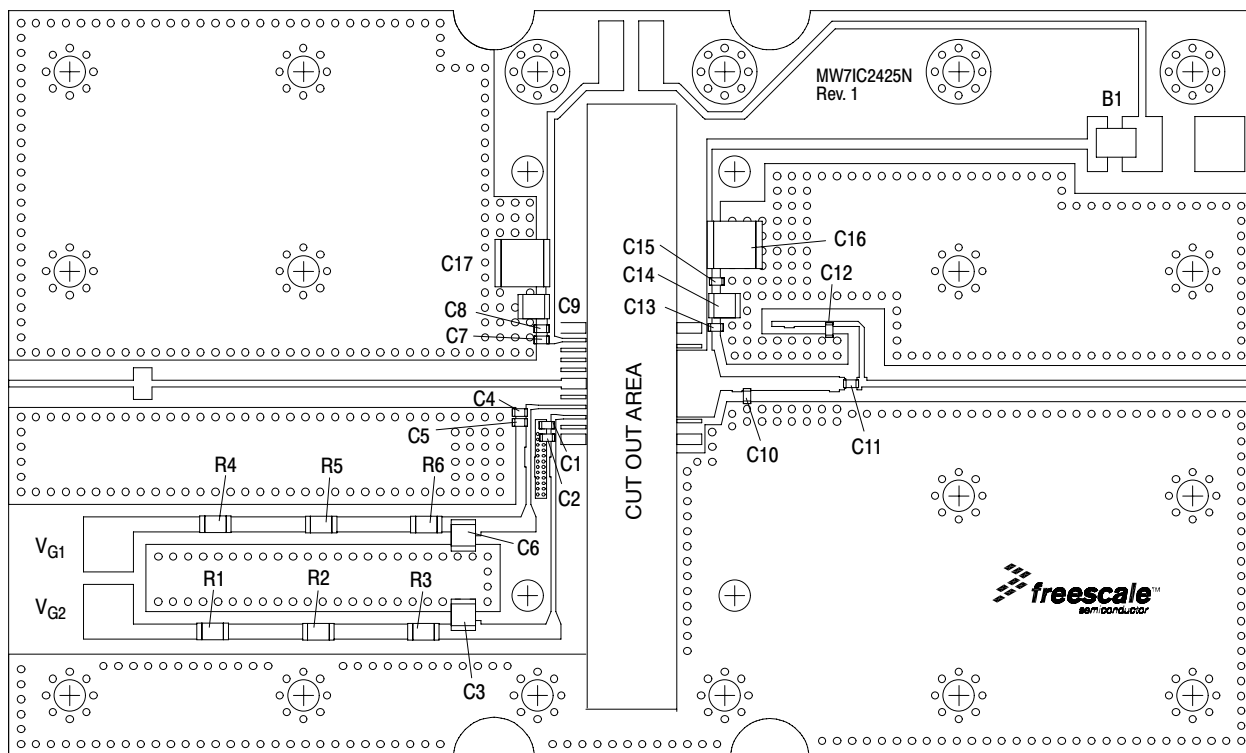


Figure 4. MW7IC2425NR1(GNR1)(NBR1) Narrowband Test Circuit Component Layout

TYPICAL CHARACTERISTICS — NARROWBAND

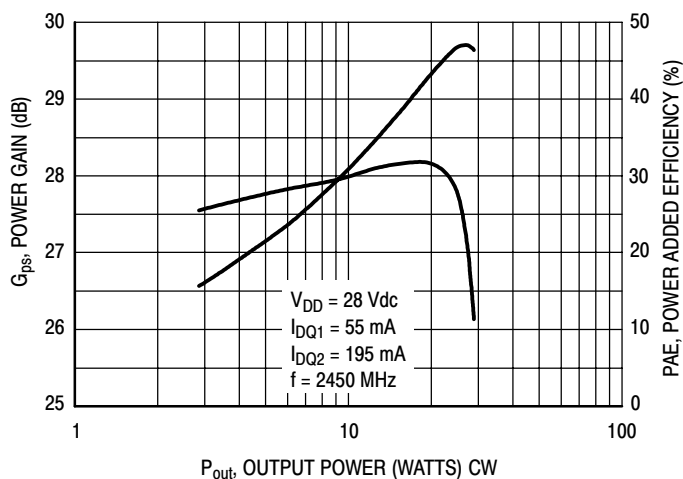


Figure 5. Power Gain and Power Added Efficiency versus CW Output Power

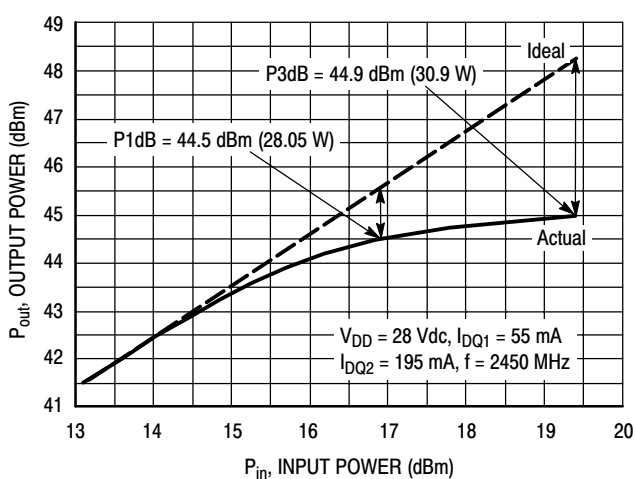


Figure 6. CW Output Power versus Input Power

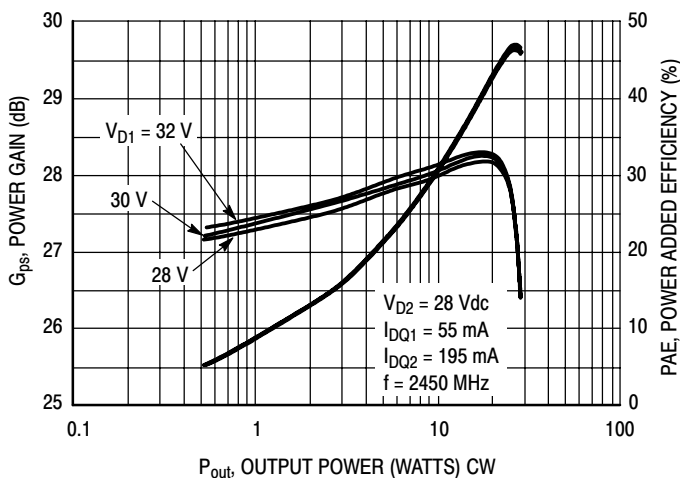


Figure 7. Power Gain and Power Added Efficiency versus CW Output Power as a Function of V_{D1}

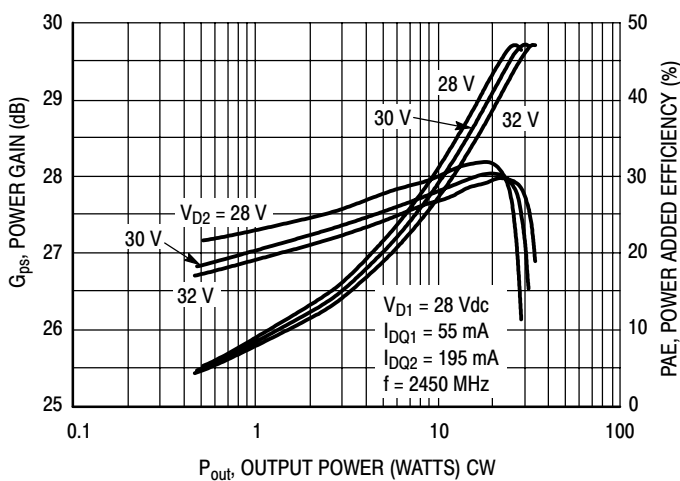


Figure 8. Power Gain and Power Added Efficiency versus CW Output Power as a Function of V_{D2}

TYPICAL CHARACTERISTICS — NARROWBAND

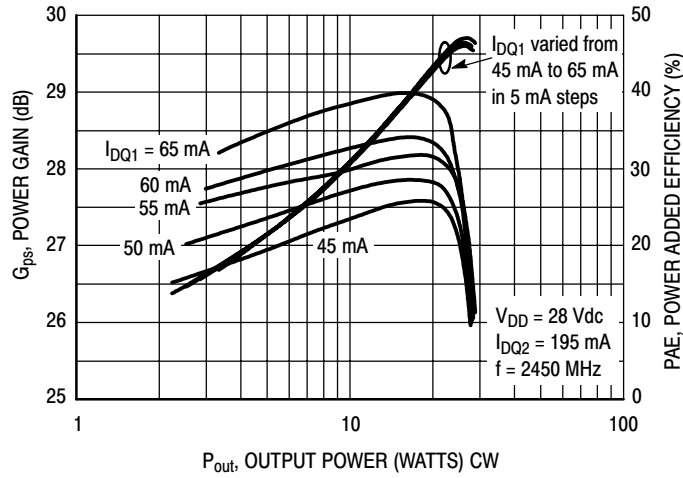


Figure 9. Power Gain and Power Added Efficiency versus CW Output Power as a Function of I_{DQ1}

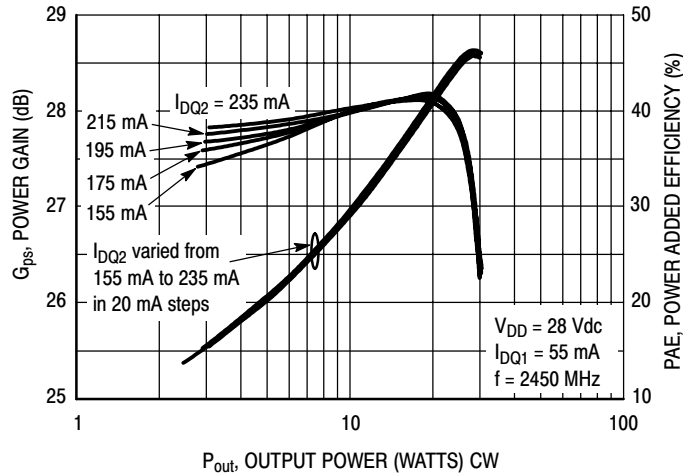
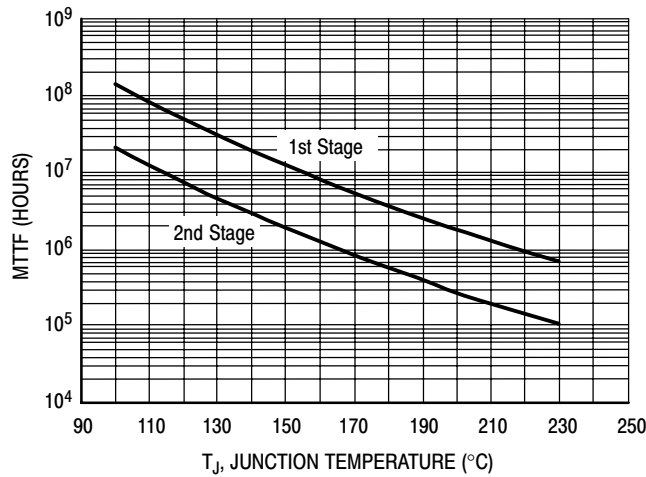


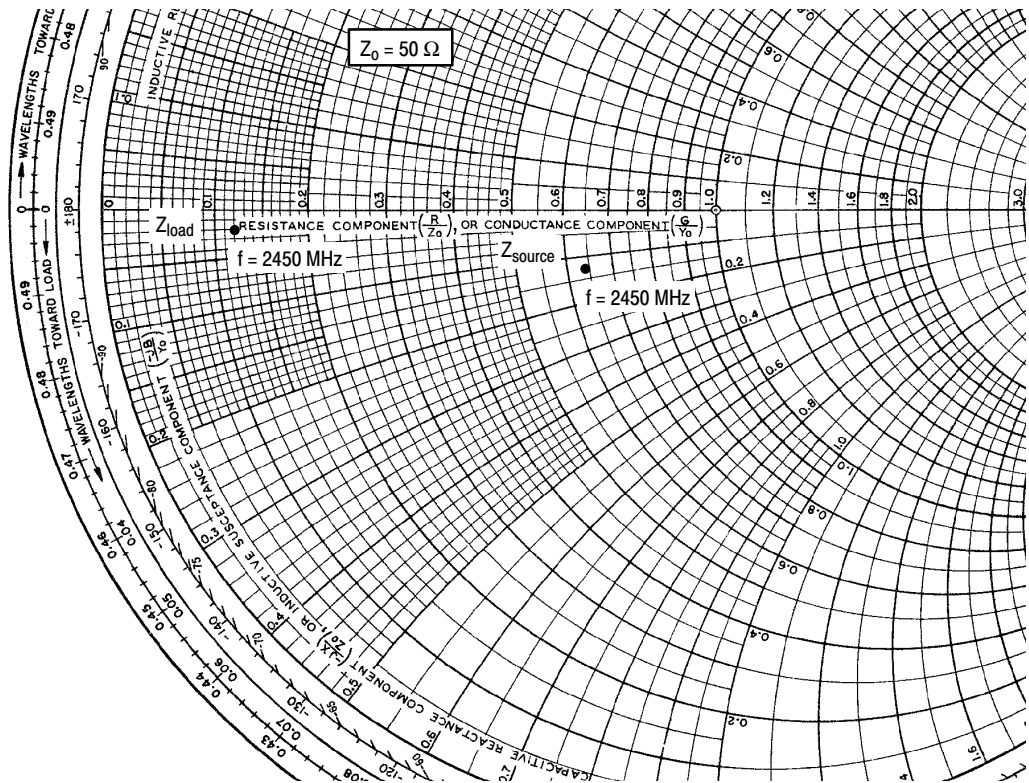
Figure 10. Power Gain and Power Added Efficiency versus CW Output Power as a Function of I_{DQ2}



This above graph displays calculated MTTF in hours when the device is operated at $V_{DD} = 28$ Vdc, $P_{out} = 25$ W CW, and PAE = 43.8%.

MTTF calculator available at <http://www.freescale.com/rf>. Select Software & Tools/Development Tools/Calculators to access MTTF calculators by product.

Figure 11. MTTF versus Junction Temperature



$V_{DD} = 28 \text{ Vdc}$, $I_{DQ1} = 55 \text{ mA}$, $I_{DQ2} = 195 \text{ mA}$, $P_{out} = 25 \text{ W CW}$

f MHz	Z_{source} Ω	Z_{load} Ω
2450	$32 - j6.256$	$6.2 - j1.17$

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.

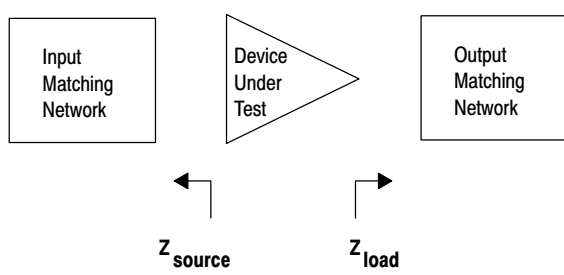
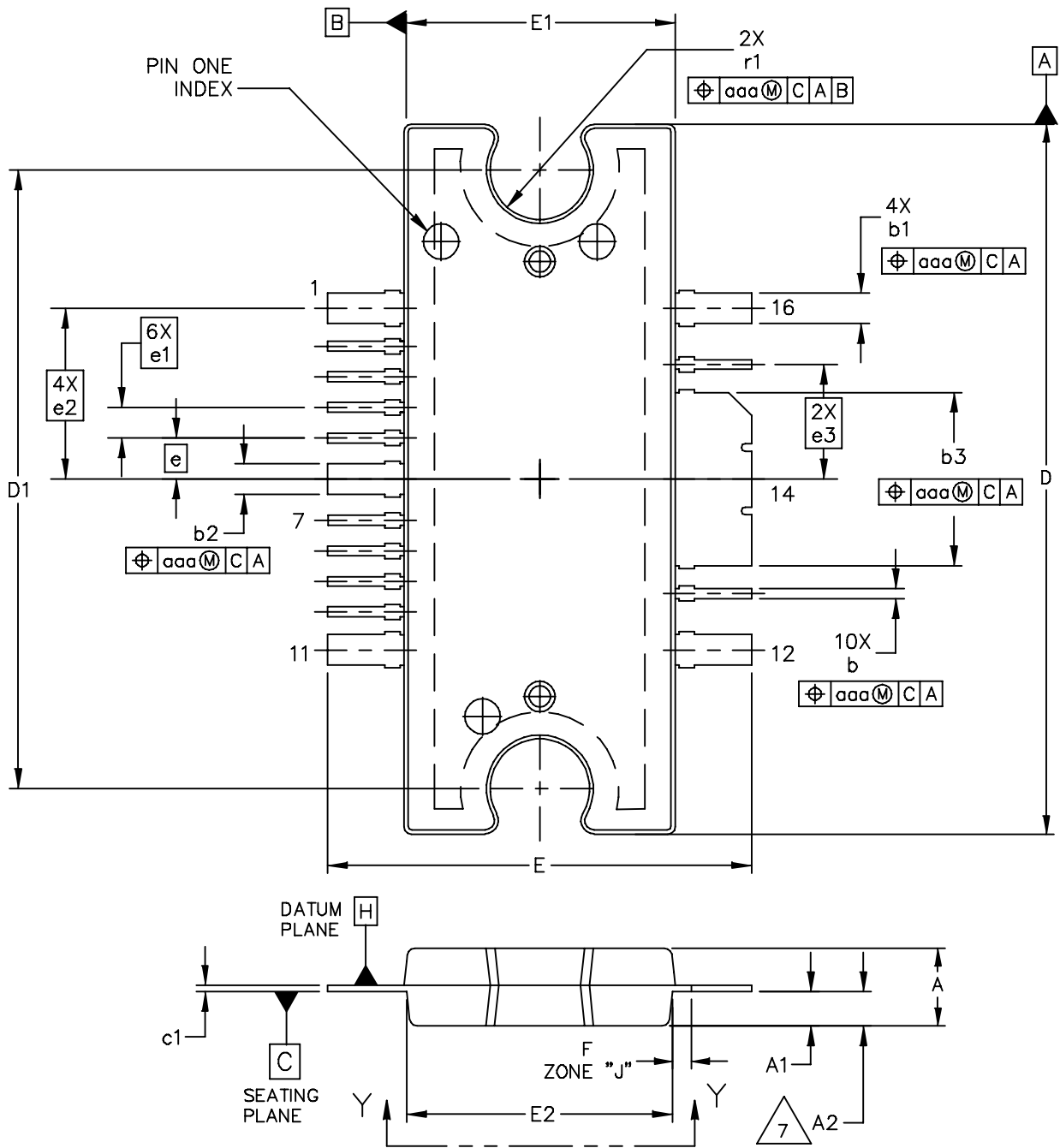
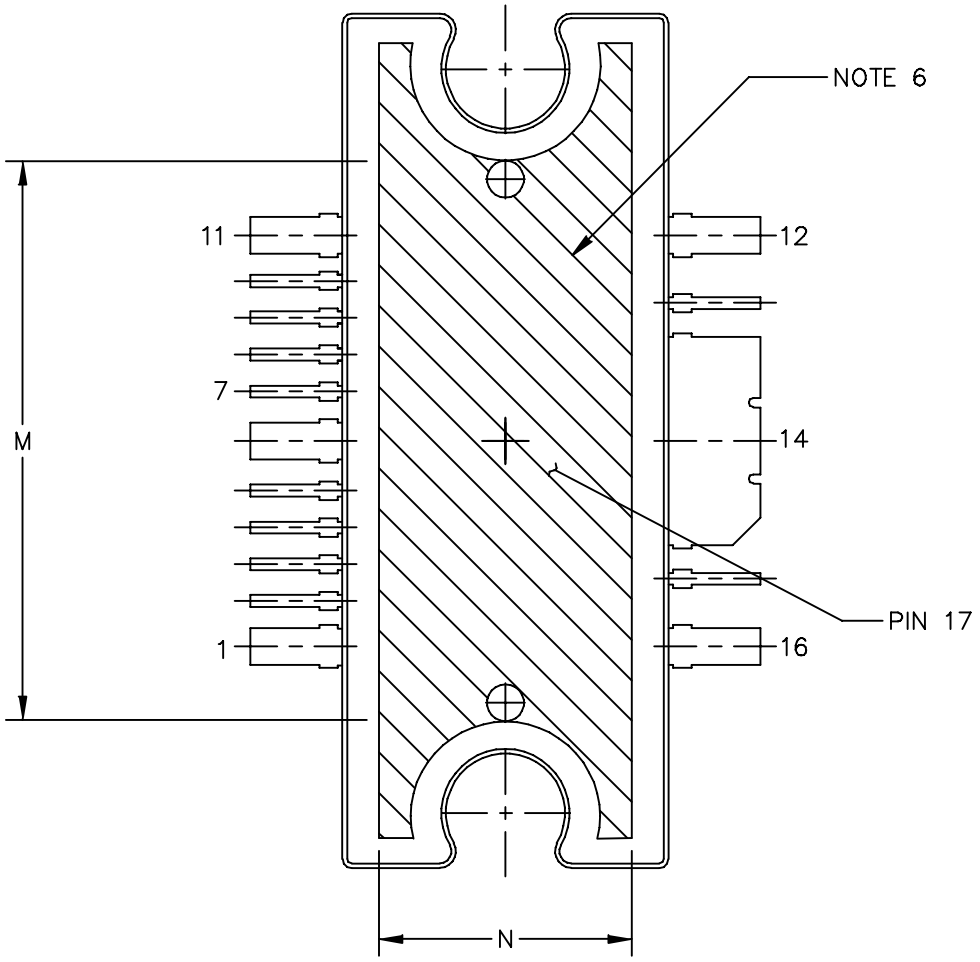


Figure 12. Series Equivalent Source and Load Impedance — Narrowband

PACKAGE DIMENSIONS



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TITLE: TO-272 WIDE BODY MULTI-LEAD			DOCUMENT NO: 98ARH99164A		REV: M
			CASE NUMBER: 1329-09		23 AUG 2007
			STANDARD: NON-JEDEC		



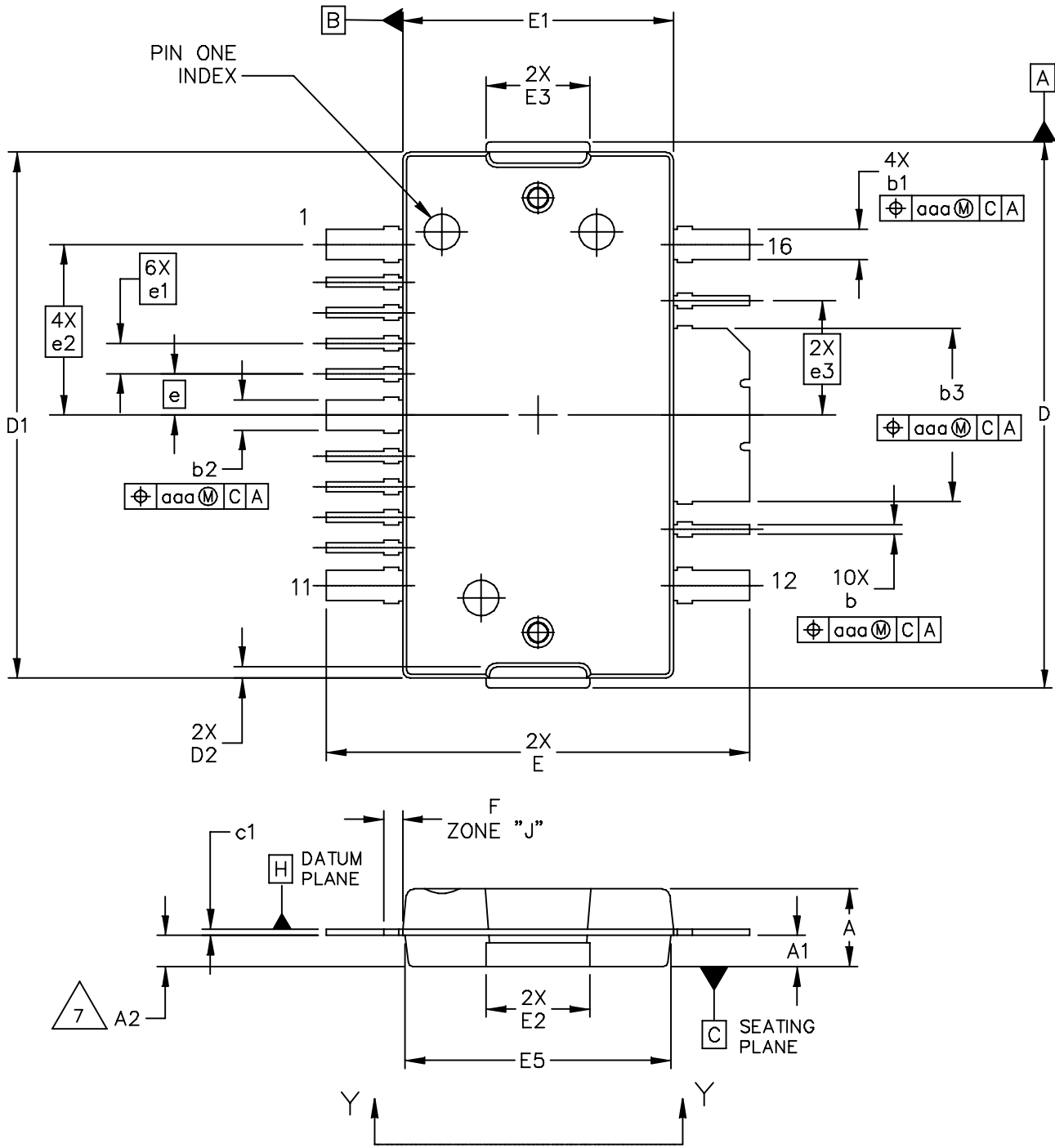
VIEW Y-Y

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	STANDARD: NON-JEDEC		

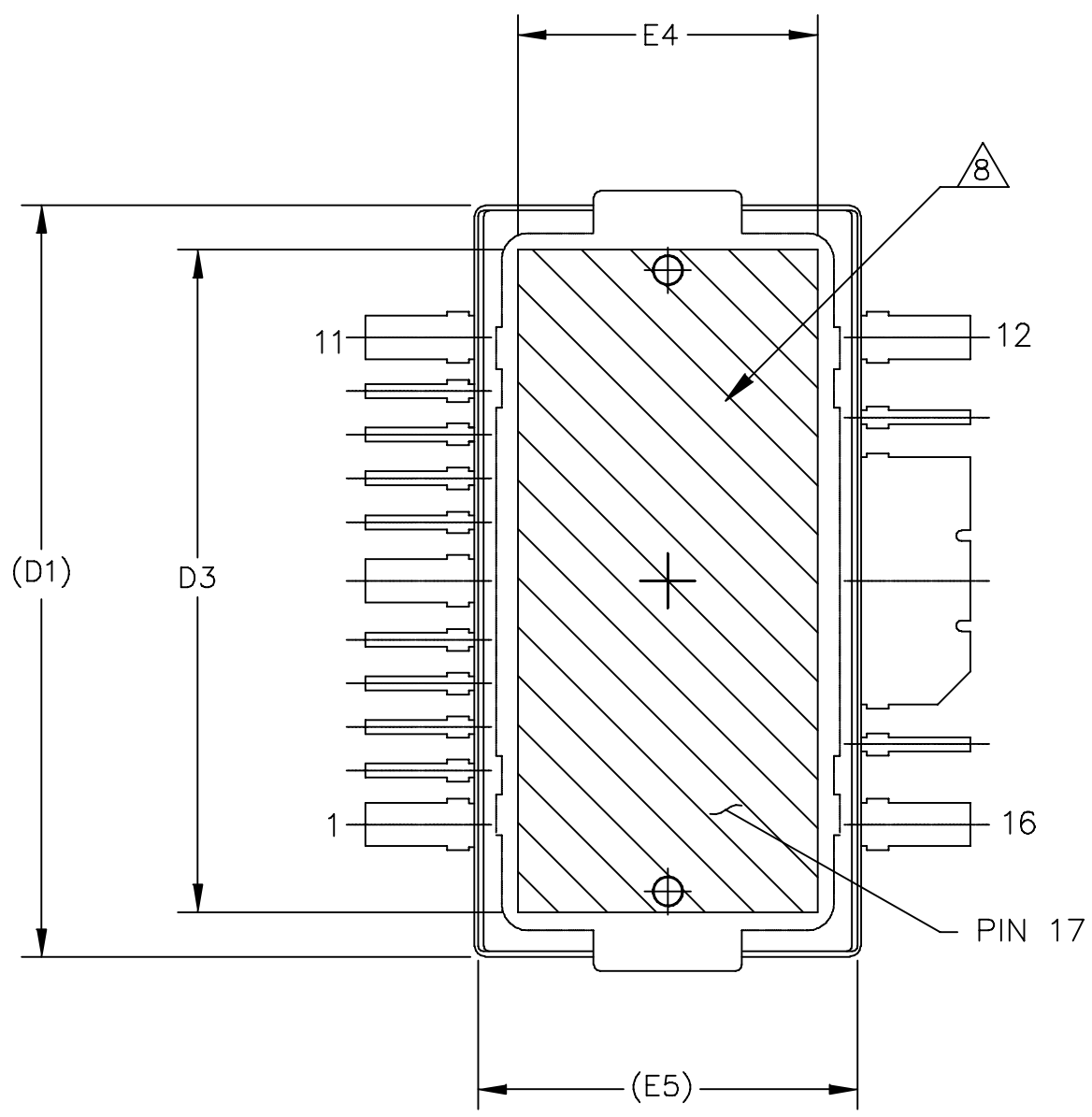
NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE -H- IS LOCATED AT THE TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 (0.15) PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
5. DIMENSIONS "b", "b1", "b2" AND "b3" DO NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 (0.13) TOTAL IN EXCESS OF THE "b", "b1", "b2" AND "b3" DIMENSIONS AT MAXIMUM MATERIAL CONDITION.
6. HATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG. HATCHED AREA SHOWN IS ON THE SAME PLANE.
7. DIM A2 APPLIES WITHIN ZONE "J" ONLY.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.100	.104	2.54	2.64	b	.011	.017	0.28	0.43
A1	.038	.044	0.96	1.12	b1	.037	.043	0.94	1.09
A2	.040	.042	1.02	1.07	b2	.037	.043	0.94	1.09
D	.928	.932	23.57	23.67	b3	.225	.231	5.72	5.87
D1	.810 BSC		20.57 BSC		c1	.007	.011	.18	.28
E	.551	.559	14.00	14.20	e	.054 BSC		1.37 BSC	
E1	.353	.357	8.97	9.07	e1	.040 BSC		1.02 BSC	
E2	.346	.350	8.79	8.89	e2	.224 BSC		5.69 BSC	
F	.025 BSC		0.64 BSC		e3	.150 BSC		3.81 BSC	
M	.600	----	15.24	----	r1	.063	.068	1.6	1.73
N	.270	----	6.86	----	aaa	.004		.10	
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	CASE NUMBER: 1886-01		31 AUG 2007
	STANDARD: NON-JEDEC		



VIEW Y-Y

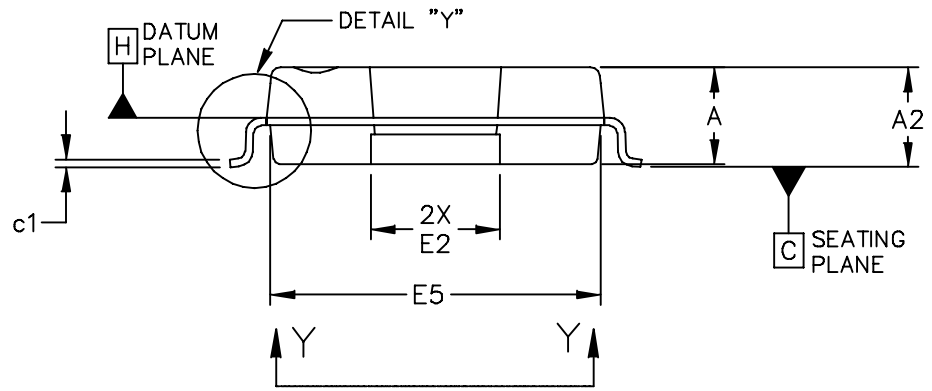
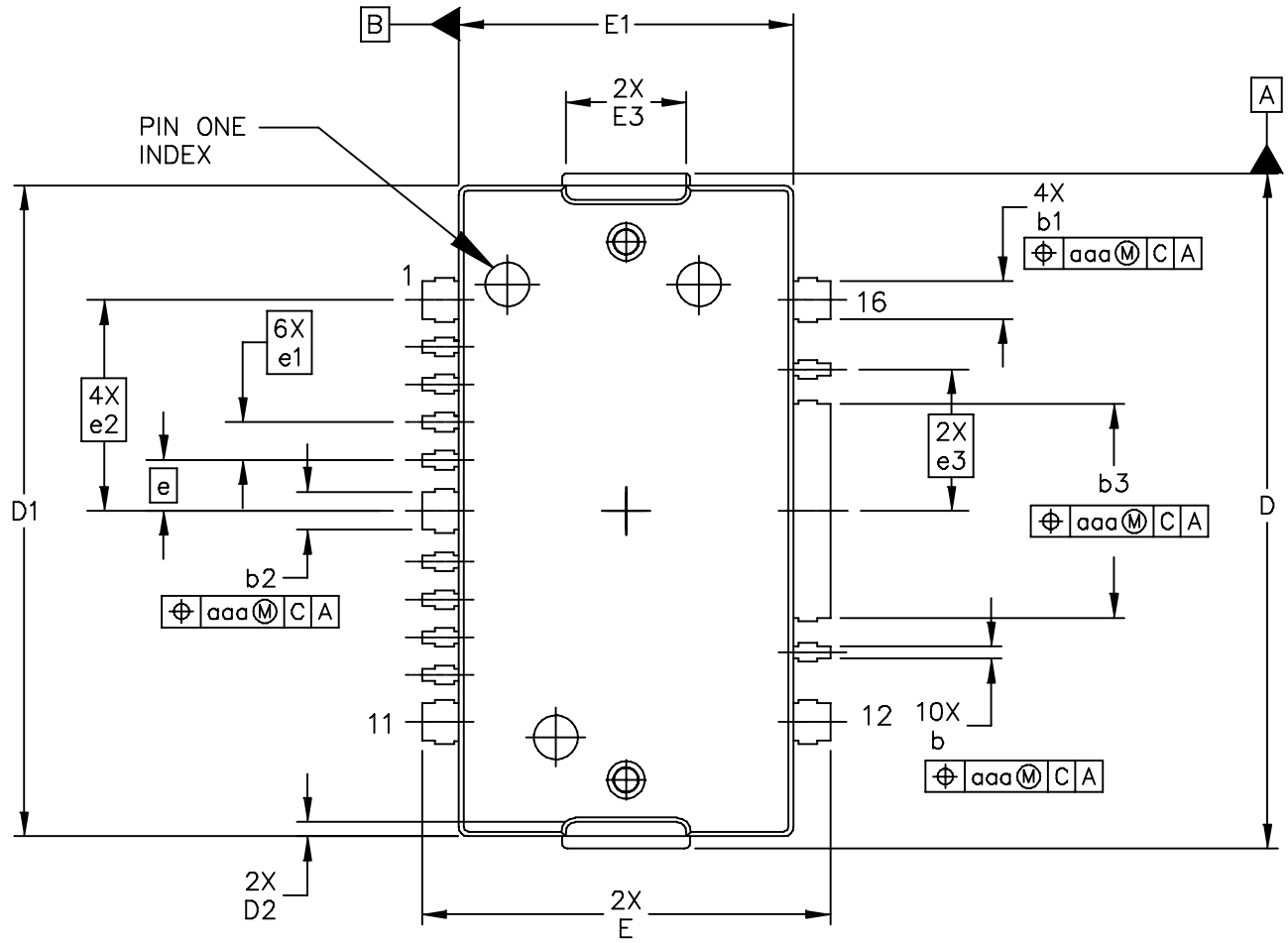
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	STANDARD: NON-JEDEC		

MW7IC2425NR1 MW7IC2425GNR1 MW7IC2425NBR1

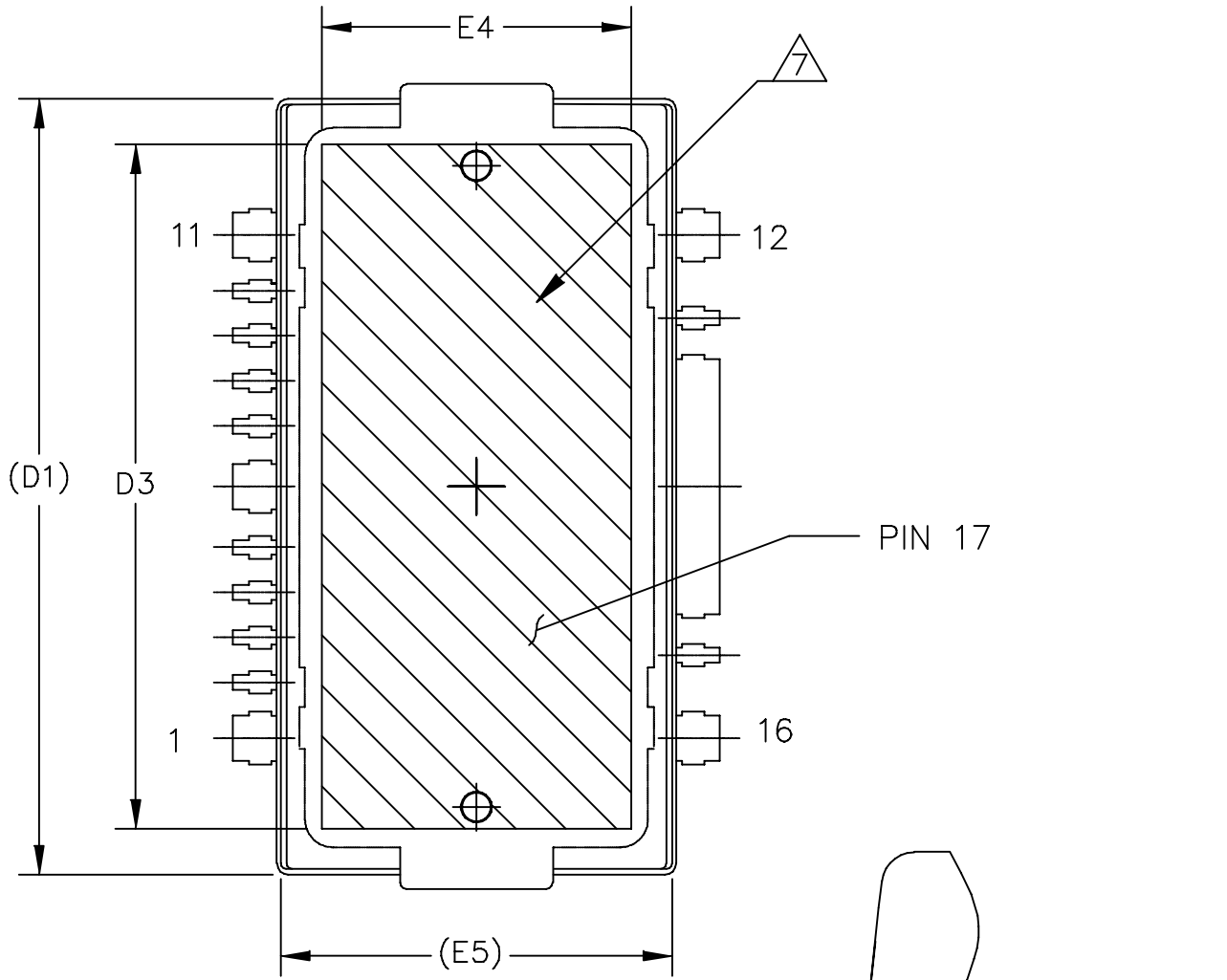
NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE -H- IS LOCATED AT THE TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 (0.15) PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
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6. DATUM -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-.
7. DIMENSION A2 APPLIES WITHIN ZONE "J" ONLY.
8. HATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG. HATCHED AREA SHOWN IS ON THE SAME PLANE.

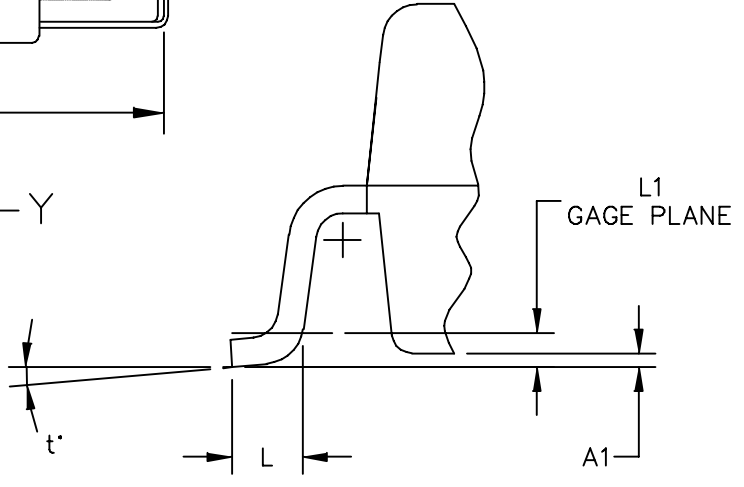
DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.100	.104	2.54	2.64	F	.025 BSC		0.64 BSC	
A1	.039	.043	0.99	1.09	b	.011	.017	0.28	0.43
A2	.040	.042	1.02	1.07	b1	.037	.043	0.94	1.09
D	.712	.720	18.08	18.29	b2	.037	.043	0.94	1.09
D1	.688	.692	17.48	17.58	b3	.225	.231	5.72	5.87
D2	.011	.019	0.28	0.48	c1	.007	.011	.18	.28
D3	.600	---	15.24	---	e	.054 BSC		1.37 BSC	
E	.551	.559	14	14.2	e1	.040 BSC		1.02 BSC	
E1	.353	.357	8.97	9.07	e2	.224 BSC		5.69 BSC	
E2	.132	.140	3.35	3.56	e3	.150 BSC		3.81 BSC	
E3	.124	.132	3.15	3.35	aaa	.004		.10	
E4	.270	---	6.86	---					
E5	.346	.350	8.79	8.89					
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					STANDARD: NON-JEDEC				



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		CASE NUMBER: 1887-01		31 AUG 2007	
		STANDARD: NON-JEDEC			



VIEW Y-Y



DETAIL "Y"

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	CASE NUMBER: 1887-01		31 AUG 2007
	STANDARD: NON-JEDEC		

NOTES:

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2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE -H- IS LOCATED AT THE TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 (0.15) PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
5. DIMENSIONS "b", "b1", "b2" AND "b3" DO NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 (0.13) TOTAL IN EXCESS OF THE "b", "b1", "b2" AND "b3" DIMENSIONS AT MAXIMUM MATERIAL CONDITION.
6. DATUM -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-.
7. HATCHING REPRESENTS EXPOSED AREA OF THE HEAT SLUG. HATCHED AREA SHOWN IS ON THE SAME PLANE.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.100	.104	2.54	2.64	L	.018	.024	0.46	0.61
A1	.001	.004	0.02	0.10	L1	.010 BSC		0.25 BSC	
A2	.099	.110	2.51	2.79	b	.011	.017	0.28	0.43
D	.712	.720	18.08	18.29	b1	.037	.043	0.94	1.09
D1	.688	.692	17.48	17.58	b2	.037	.043	0.94	1.09
D2	.011	.019	0.28	0.48	b3	.225	.231	5.72	5.87
D3	.600	---	15.24	---	c1	.007	.011	0.18	0.28
E	.429	.437	10.9	11.1	e	.054 BSC		1.37 BSC	
E1	.353	.357	8.97	9.07	e1	.040 BSC		1.02 BSC	
E2	.132	.140	3.35	3.56	e2	.224 BSC		5.69 BSC	
E3	.124	.132	3.15	3.35	e3	.150 BSC		3.81 BSC	
E4	.270	---	6.86	---	t	2'	8'	2'	8'
E5	.346	.350	8.79	8.89	aaa	.004		0.10	
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TITLE: TO-270 WIDE BODY 16 LEAD, GULL WING					DOCUMENT NO: 98ASA10755D			REV: A	
					CASE NUMBER: 1887-01			31 AUG 2007	
					STANDARD: NON-JEDEC				

PRODUCT DOCUMENTATION

Refer to the following documents to aid your design process.

Application Notes

- AN1907: Solder Reflow Attach Method for High Power RF Devices in Plastic Packages
- AN1955: Thermal Measurement Methodology of RF Power Amplifiers
- AN1977: Quiescent Current Thermal Tracking Circuit in the RF Integrated Circuit Family
- AN1987: Quiescent Current Control for the RF Integrated Circuit Device Family
- AN3263: Bolt Down Mounting Method for High Power RF Transistors and RFICs in Over-Molded Plastic Packages
- AN3789: Clamping of High Power RF Transistors and RFICs in Over-Molded Plastic Packages

Engineering Bulletins

- EB212: Using Data Sheet Impedances for RF LDMOS Devices

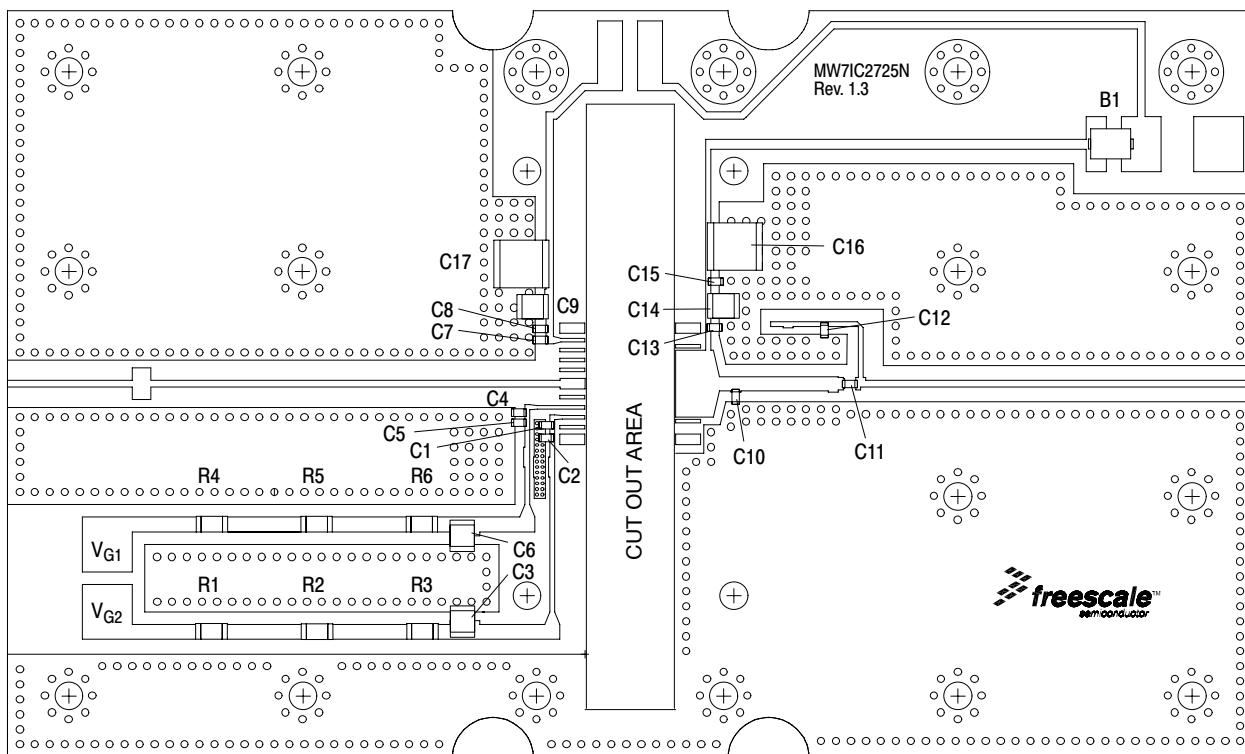
REVISION HISTORY

The following table summarizes revisions to this document.

Revision	Date	Description
0	Mar. 2009	<ul style="list-style-type: none"> • Initial Release of Data Sheet

APPENDIX A

MW7IC2425NR1/GNR1/NBR1 FUNCTIONAL TEST DATA, FIXTURE AND THERMAL DATA



- | | | | |
|----|--------------------------------|------|--|
| Z1 | 0.500" x 0.027" Microstrip | Z9 | 0.040" x 0.061" Microstrip |
| Z2 | 0.075" x 0.127" Microstrip | Z10 | 0.020" x 0.050" Microstrip |
| Z3 | 1.640" x 0.027" Microstrip | Z11 | 0.050" x 0.050" Microstrip |
| Z4 | 0.100" x 0.042" Microstrip | Z12 | 0.050" x 0.027" Microstrip |
| Z5 | 0.151" x 0.268" Microstrip | Z13* | 0.338" x 0.020" Microstrip |
| Z6 | 0.025" x 0.268" x 0.056" Taper | Z14 | 1.551" x 0.027" Microstrip |
| Z7 | 0.050" x 0.056" Microstrip | PCB | Rogers R04350B, 0.0133", $\epsilon_r = 3.48$ |
| Z8 | 0.356" x 0.056" Microstrip | | |
- * Line length includes microstrip bends

Figure 1. MW7IC2425NR1(GNR1)(NBR1) Test Circuit Component Layout

Table 1. Electrical Characteristics (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Power Gain	G _{ps}	25.5	28.5	30.5	dB
Power Added Efficiency	PAE	15	17	—	%
Output Peak-to-Average Ratio @ 0.01% Probability on CCDF	PAR	—	9	—	dB
Adjacent Channel Power Ratio	ACPR	—	-50	-46	dBc
Input Return Loss	IRL	—	-15	-10	dB

(continued)

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+46 8 52200080 (English)
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Japan:

Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku,
Tokyo 153-0064
Japan
0120 191014 or +81 3 5437 9125
support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor China Ltd.
Exchange Building 23F
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China
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